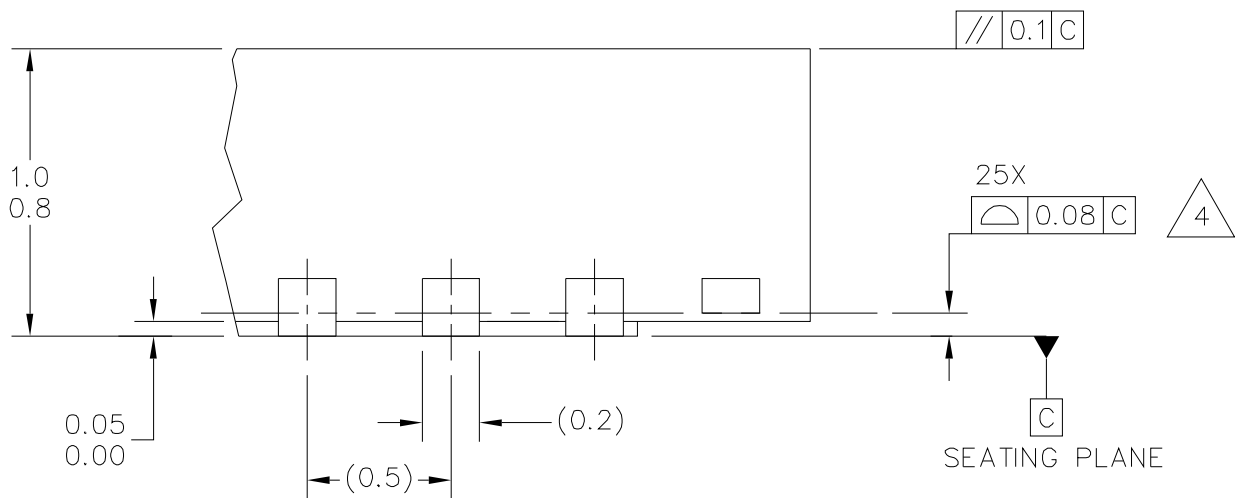


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TITLE: QFN, THERMALLY ENHANCED 4 X 4 X 0.9, 0.5 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00474D		REV: A
	CASE NUMBER: 2296-02		11 OCT 2012
	STANDARD: NON-JEDEC		



DETAIL F
VIEW ROTATED 90°CW

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MECHANICAL OUTLINE

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TITLE:
QFN, THERMALLY ENHANCED
4 X 4 X 0.9, 0.5 PITCH, 24 TERMINAL

DOCUMENT NO: 98ASA00474D


REV: A

CASE NUMBER: 2296-02

11 OCT 2012

STANDARD: NON-JEDEC

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THIS IS A NON–JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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